# onsemi

# MOSFET – Power, N-Channel, SUPERFET<sup>®</sup> III, FRFET<sup>®</sup>

V <sub>DSS</sub>	R <sub>DS(on)</sub> MAX	I <sub>D</sub> MAX
650 V	190 mΩ @ 10 V	20 A

# 650 V, 20 A, 190 m $\Omega$

# NTHL190N65S3HF

#### Description

SUPERFET III MOSFET is **onsemi**'s brand-new high voltage super-junction (SJ) MOSFET family that is utilizing charge balance technology for outstanding low on-resistance and lower gate charge performance. This advanced technology is tailored to minimize conduction loss, provide superior switching performance, and withstand extreme dv/dt rate.

Consequently, SUPERFET III MOSFET is very suitable for the various power system for miniaturization and higher efficiency.

SUPERFET III FRFET MOSFET's optimized reverse recovery performance of body diode can remove additional component and improve system reliability.

#### Features

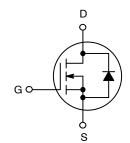
- 700 V @  $T_J = 150^{\circ}C$
- Typ.  $R_{DS(on)} = 165 \text{ m}\Omega$
- Ultra Low Gate Charge (Typ.  $Q_g = 34 \text{ nC}$ )
- Low Effective Output Capacitance (Typ. Coss(eff.) = 316 pF)
- 100% Avalanche Tested
- These Devices are Pb-Free and are RoHS Compliant

#### Applications

- Telecom / Server Power Supplies
- Industrial Power Supplies
- EV Charger
- UPS / Solar

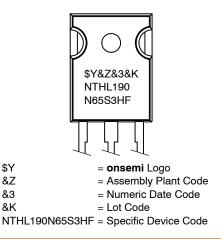


TO-247-3LD CASE 340CX



**N-Channel MOSFET** 

#### MARKING DIAGRAM



#### **ORDERING INFORMATION**

See detailed ordering and shipping information on page 8 of this data sheet.

Symbol	Parameter	Value	Unit		
V <sub>DSS</sub>	Drain to Source Voltage	650	V		
V <sub>GSS</sub>	Gate to Source Voltage DC		±30	V	
		AC (f > 1 Hz)	±30	V	
I <sub>D</sub>	Drain Current	Continuous (T <sub>C</sub> = 25°C)	20	А	
		Continuous (T <sub>C</sub> = 100°C)	12.7	1	
I <sub>DM</sub>	Drain Current	Pulsed (Note 1)	50	А	
E <sub>AS</sub>	Single Pulsed Avalanche Energy (Note 2)		220	mJ	
I <sub>AS</sub>	Avalanche Current (Note 2)		3.7	А	
E <sub>AR</sub>	Repetitive Avalanche Energy (Note 1)		1.62	mJ	
dv/dt	MOSFET dv/dt		100	V/ns	
	Peak Diode Recovery dv/dt (Note 3)	50			
P <sub>D</sub>	Power Dissipation	(T <sub>C</sub> = 25°C)	162	W	
		Derate Above 25°C	1.3	W/°C	
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature Range		–55 to +150	°C	
ΤL	Maximum Lead Temperature for Soldering, 1/8" from Case for 5 s		300	°C	

#### ABSOLUTE MAXIMUM RATINGS (T<sub>C</sub> = 25°C, Unless otherwise specified)

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected. 1. Repetitive rating: pulse-width limited by maximum junction temperature. 2.  $I_{AS} = 3.7 \text{ A}, R_G = 25 \Omega$ , starting  $T_J = 25^{\circ}\text{C}$ . 3.  $I_{SD} \le 10 \text{ A}, \text{ di/dt} \le 200 \text{ A/}\mu\text{s}, \text{ V}_{DD} \le 400 \text{ V}, \text{ starting } T_J = 25^{\circ}\text{C}$ .

#### **THERMAL CHARACTERISTICS**

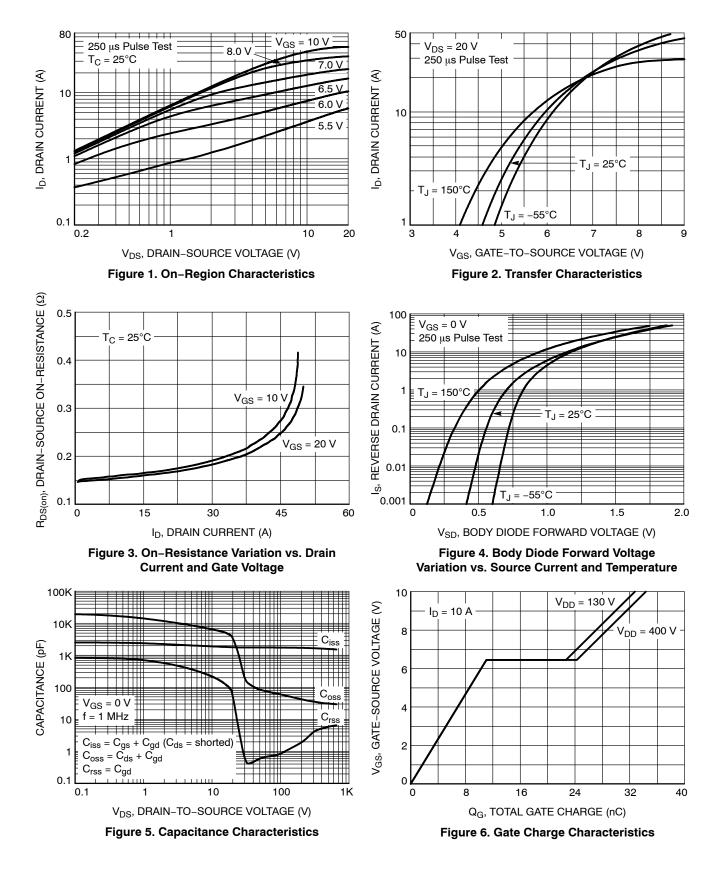
Symbol	Parameter	Value	Unit
$R_{ ext{ heta}JC}$	Thermal Resistance, Junction to Case, Max.	0.77	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient, Max.	40	

#### ELECTRICAL CHARACTERISTICS (T<sub>C</sub> = 25°C unless otherwise noted)

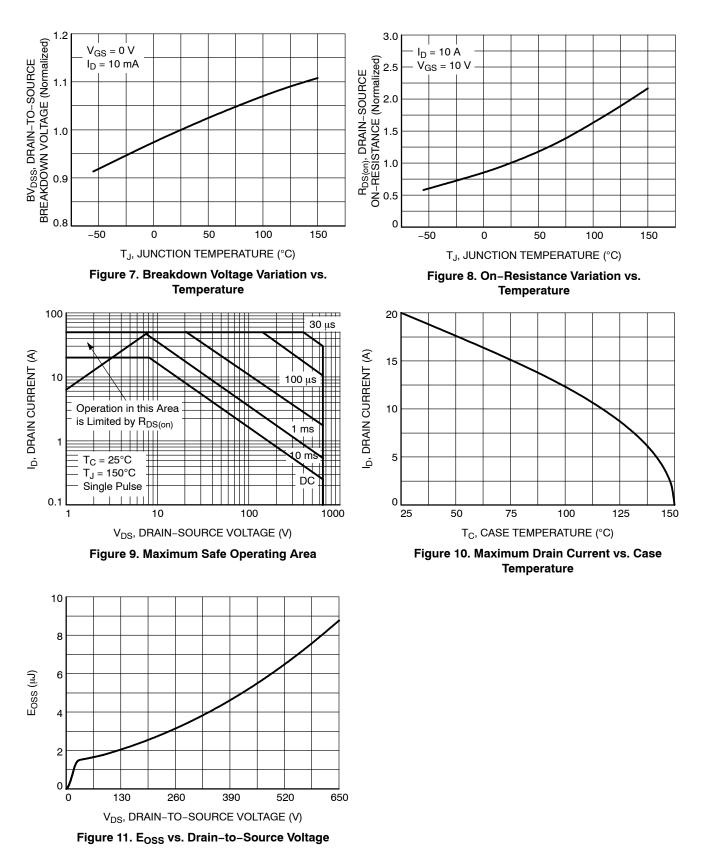
Symbol	Parameter	Test Conditions	Min	Тур	Max	Unit
OFF CHARACT	ERISTICS		•			
BV <sub>DSS</sub>	Drain to Source Breakdown Voltage	$V_{GS}$ = 0 V, $I_D$ = 1 mA, $T_J$ = 25°C	650			V
		$V_{GS}$ = 0 V, I <sub>D</sub> = 1 mA, T <sub>J</sub> = 150°C	700			V
$\Delta \text{BV}_{\text{DSS}}\!/\!\Delta\text{T}_{\text{J}}$	Breakdown Voltage Temperature Coefficient	$I_D = 10$ mA, Referenced to 25°C		0.65		V/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	$V_{DS}$ = 650 V, $V_{GS}$ = 0 V			10	μΑ
		$V_{DS}$ = 520 V, $T_C$ = 125°C		65		
I <sub>GSS</sub>	Gate to Body Leakage Current	$V_{GS}$ = ±30 V, $V_{DS}$ = 0 V			±100	nA
ON CHARACTE	RISTICS					-
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{GS} = V_{DS}$ , $I_D = 0.43$ mA	3.0		5.0	V
R <sub>DS(on)</sub>	Static Drain to Source On Resistance	$V_{GS}$ = 10 V, I <sub>D</sub> = 10 A		165	190	mΩ
9fs	Forward Transconductance	$V_{DS} = 20 \text{ V}, \text{ I}_{D} = 10 \text{ A}$		11		S
YNAMIC CHA	RACTERISTICS		•			
C <sub>iss</sub>	Input Capacitance			1610		pF
Coss	Output Capacitance	V <sub>DS</sub> = 400 V, V <sub>GS</sub> = 0 V, f = 1 MHz		30		pF
C <sub>oss(eff.)</sub>	Effective Output Capacitance	$V_{DS}$ = 0 V to 400 V, $V_{GS}$ = 0 V		316		pF
C <sub>oss(er.)</sub>	Energy Related Output Capacitance	$V_{DS}$ = 0 V to 400 V, $V_{GS}$ = 0 V		59		pF
Q <sub>g(tot)</sub>	Total Gate Charge at 10 V			34		nC
Q <sub>gs</sub>	Gate to Source Gate Charge	V <sub>DS</sub> = 400 V, I <sub>D</sub> = 10 A, V <sub>GS</sub> = 10 V (Note 4)		11		nC
Q <sub>gd</sub>	Gate to Drain "Miller" Charge			13		nC
ESR	Equivalent Series Resistance	f = 1 MHz		6.8		Ω
WITCHING CH	IARACTERISTICS					
t <sub>d(on)</sub>	Turn-On Delay Time			19		ns
t <sub>r</sub>	Turn-On Rise Time	$V_{DD} = 400 \text{ V}, \text{ I}_{D} = 10 \text{ A},$		19		ns
t <sub>d(off)</sub>	Turn-Off Delay Time	$\begin{array}{c} {\sf V}_{\rm DD} = 400 \; {\sf V}, \; {\sf I}_{\rm D} = 10 \; {\sf A}, \\ {\sf V}_{\rm GS} = 10 \; {\sf V}, \; {\sf R}_{\rm g} = 4.7 \; \Omega \\ \qquad \qquad$		58		ns
t <sub>f</sub>	Turn-Off Fall Time			14		ns
OURCE-DRAI	N DIODE CHARACTERISTICS		•			
۱ <sub>S</sub>	Maximum Continuous Source to Drain Diode Forward Current				20	Α
I <sub>SM</sub>	Maximum Pulsed Source to Drain Diode Forward Current				50	А
$V_{SD}$	Source to Drain Diode Forward Voltage	$V_{GS}$ = 0 V, $I_{SD}$ = 10 A			1.3	V
t <sub>rr</sub>	Reverse Recovery Time	V <sub>DD</sub> = 400 V, I <sub>SD</sub> = 10 A,		80		ns
Q <sub>rr</sub>	Reverse Recovery Charge	$dI_F/dt = 100 \text{ A}/\mu\text{s}$		264		nC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions. 4. Essentially independent of operating temperature typical characteristics.

#### **TYPICAL CHARACTERISTICS**



#### TYPICAL CHARACTERISTICS (continued)



#### TYPICAL CHARACTERISTICS (continued)

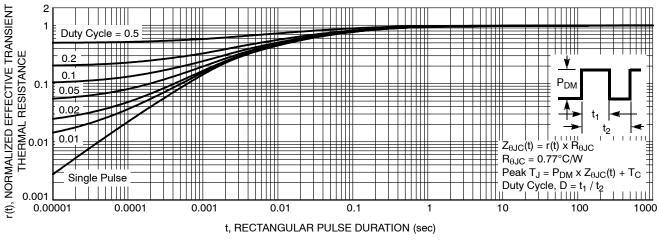
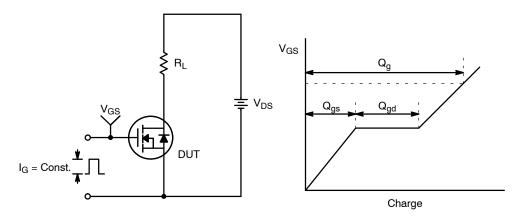


Figure 12. Transient Thermal Response Curve





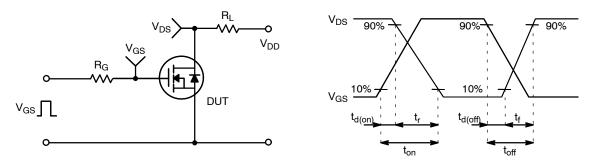
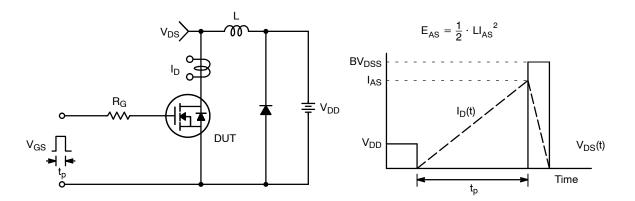


Figure 14. Resistive Switching Test Circuit & Waveforms





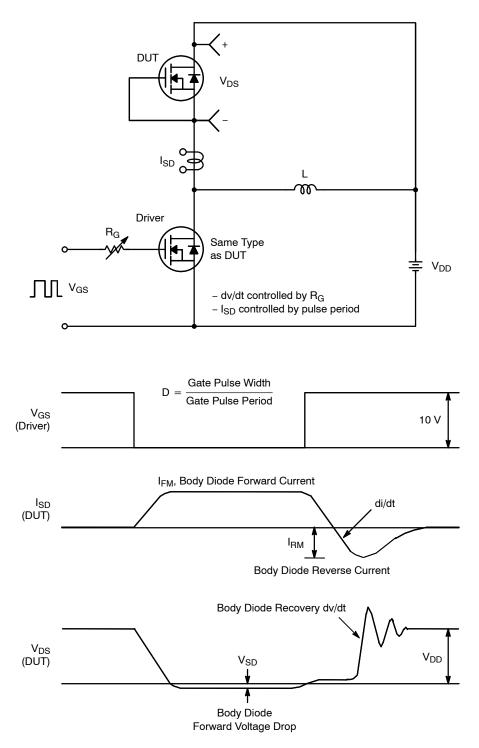


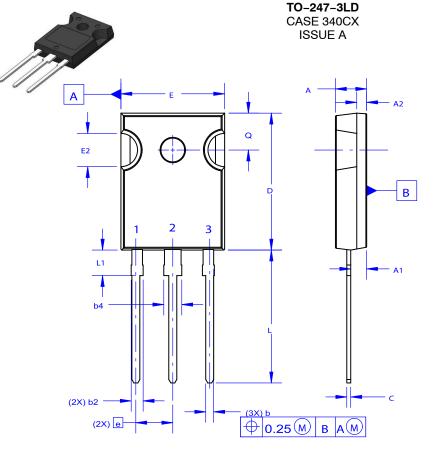
Figure 16. Peak Diode Recovery dv/dt Test Circuit & Waveforms

#### PACKAGE MARKING AND ORDERING INFORMATION

Part Number	Top Marking	Package	Packing Method	Reel Size	Tape Width	Quantity
NTHL190N65S3HF	NTHL190N65S3HF	TO-247	Tube	N/A	N/A	30 Units

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NOTES: UNLESS OTHERWISE SPECIFIED.

- A. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- B. ALL DIMENSIONS ARE IN MILLIMETERS.
- C. DRAWING CONFORMS TO ASME Y14.5 2009.
- D. DIMENSION A1 TO BE MEASURED IN THE REGION DEFINED BY L1.
- E. LEAD FINISH IS UNCONTROLLED IN THE REGION DEFINED BY L1.

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# GENERIC **MARKING DIAGRAM\*** Х



XXXXX	= Specific Device Code
Α	= Assembly Location

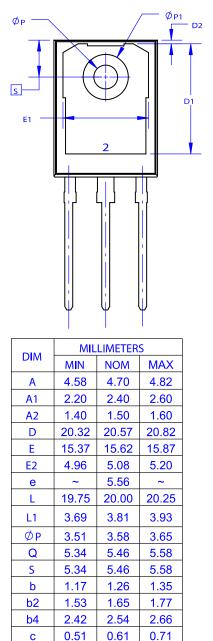
- = Assembly Location
- = Year
- ww = Work Week
- G = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ", may or may not be present. Some products may not follow the Generic Marking.

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DESCRIPTION:	TO-247-3LD		PAGE 1 OF 1

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DATE 06 JUL 2020



D1

D2

E1

ØP1

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6.60

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